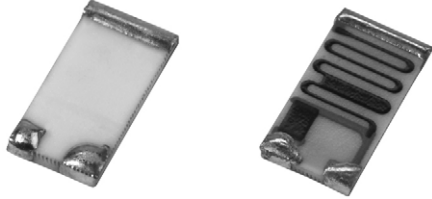


## Thick Film Chip Dividers, High Voltage



### FEATURES

- High voltage up to 3000 V
- Typical resistance ratios of 250:1, 500:1, etc.; maximum resistance ratio of 800:1
- Flow solderable
- Tape and reel packaging available
- Termination style: 3-sided wraparound termination or single termination flip chip available
- Suitable for solderable, epoxy bondable, or wire bondable applications
- Termination material: solder-coated nickel barrier or solder coated non-magnetic terminations standard; gold, palladium silver, platinum gold, platinum silver or platinum palladium gold terminations available
- Multiple styles, termination materials and configurations, allow wide design flexibility
- Epoxy bondable or wire bondable non-magnetic terminations available
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



### Note

\* This datasheet provides information about parts that are RoHS-compliant and/or parts that are non-RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details.

STANDARD ELECTRICAL SPECIFICATIONS							
GLOBAL MODEL	CASE SIZE	POWER RATING $P_{70^{\circ}\text{C}}$ W	MAXIMUM WORKING VOLTAGE <sup>(1)</sup> V	RESISTANCE RANGE <sup>(2)</sup> $\Omega$	TOLERANCE <sup>(3)</sup> $\pm$ %	TEMPERATURE COEFFICIENT <sup>(4)</sup> (-55 °C to +155 °C) $\pm$ ppm/°C	TCR TRACKING $\pm$ ppm/°C
CDHV 2512	2512	1	3000	20M to 20G	1, 2, 5, 10, 20	100	50 (typical)

### Notes

- (1) Continuous working voltage shall be  $\sqrt{P \times R}$  or maximum working voltage, whichever is less.
- (2) Resistance values below 1 G $\Omega$  are calibrated at 100 V<sub>DC</sub>, and values of 1 G $\Omega$  and above are calibrated at 1000 V<sub>DC</sub>. Calibration at other voltages available upon request.
- (3) Contact factory for tighter tolerances.
- (4) Reference only: not for all values specified. Consult factory for your value.

VOLTAGE AND TEMPERATURE COEFFICIENTS OF RESISTANCE CHART TYPICAL			
RESISTANCE ( $\Omega$ )	RATIO (TYPICAL)	VCR (ppm/V)	TCR (ppm/°C) -55 °C to +155 °C
20M	250:1	10	100
150M	300:1	10	150
800M	500:1	10	200

### Note

- Contact factory for other ratios.

GLOBAL PART NUMBER INFORMATION																	
New Global Part Numbering: CDHVAF20M0J2500GFB (preferred part number format)																	
C	D	H	V	A	F	2	0	M	0	J	2	5	0	0	G	F	B
GLOBAL MODEL	TERM STYLE	TERM MATERIAL		RESISTANCE VALUE (R1)		TOLERANCE		RATIO R1/R2		RATIO TOLERANCE		SOLDER TERMINATION		PACKAGING			
CDHV = CDHV2512	A = 3-sided B = top only	F = nickel barrier G = non-magnetic A = palladium silver B = platinum gold C = gold D = platinum silver E = platinum palladium gold		M = MΩ G = GΩ 20M0 = 20 MΩ 800M = 800 MΩ 1G00 = 1 GΩ		F = ± 1 % G = ± 2 % J = ± 5 % K = ± 10 % M = ± 20 %		3 digit significant figure, followed by a multiplier 0500 = 50:1 2500 = 250:1 3000 = 300:1 5000 = 500:1		G = ± 2 % H = ± 3 % J = ± 5 %		E = Sn100 F = Sn95/Ag5, HSD N = no solder S = Sn62 / Pb36 / Ag2, HSD T = Sn90 / Pb10		B = bulk F = T / R (full reel) 1 = T / R (1000 pcs) 5 = T / R (500 pcs) T = T / R (250 pcs min.) W = waffle tray			
Historical Part Numbering: CDHV2512AF2005J2500Ge2 (will continue to be accepted)																	
CDHV2512	A	F	2005	J	2500	G	e2										
HISTORICAL MODEL	TERM STYLE	TERM MATERIAL	RESISTANCE VALUE (R1)	TOLERANCE	RATIO R1/R2	RATIO TOLERANCE	SOLDER TERMINATION										

**Note**

- For additional information on packaging, refer to the “Surface Mount Resistor Packaging” document ([www.vishay.com/doc?31543](http://www.vishay.com/doc?31543)).

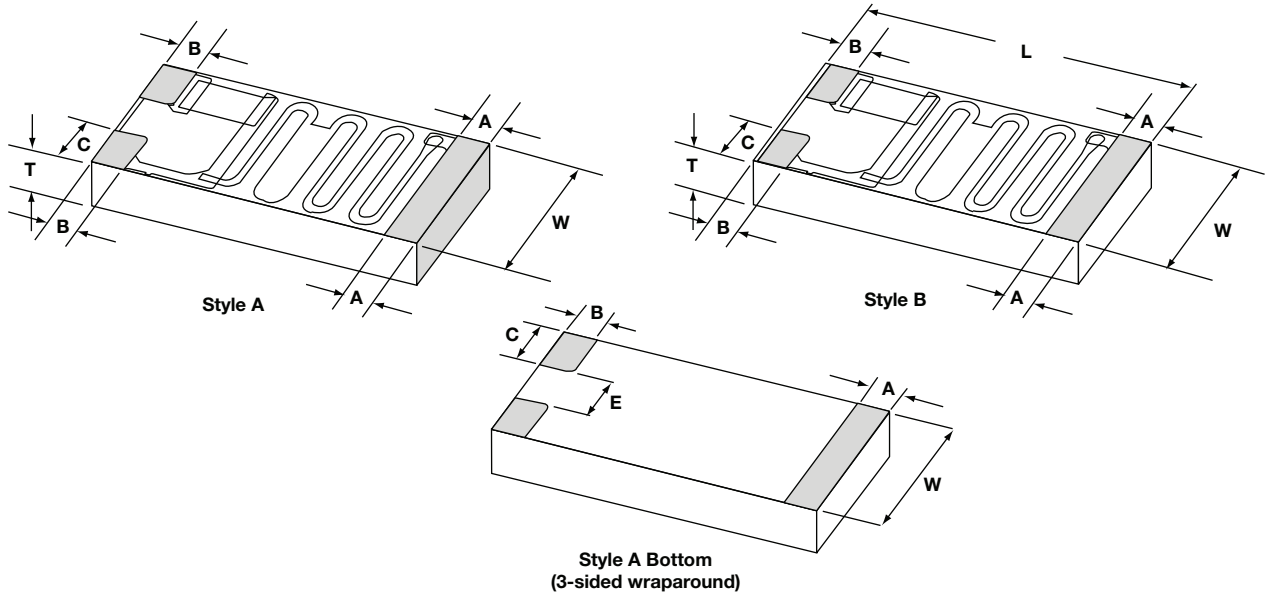
MATERIAL SPECIFICATIONS	
Resistive element	Ruthenium oxide
Encapsulation	Glass
Substrate	96 % alumina
Termination	Solder-coated nickel barrier or solder coated non-magnetic terminations standard. Gold, palladium silver, platinum gold, platinum silver, platinum palladium gold terminations available.
Solder finish	Pure tin or tin / lead solder alloys standard. Tin / silver or tin / lead / silver solder alloys available.

ENVIRONMENTAL SPECIFICATIONS	
Operating temperature	-55 °C to +155 °C
Life	Less than 0.5 % change when tested at full rated power

**Note**

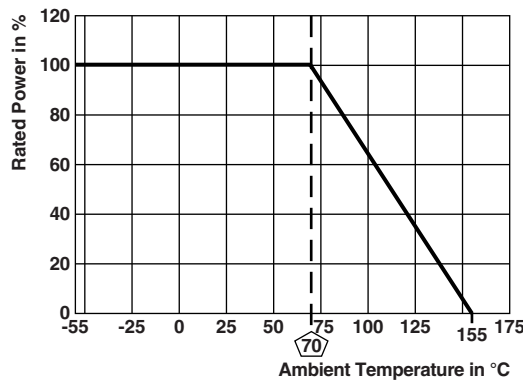
- Reference only: not for all values specified. Consult factory for your size and value.

**DIMENSIONS** in inches (millimeters)



TERMINATION	LENGTH (L) ± 0.006 (0.152)	WIDTH (W) ± 0.006 (0.152)	THICKNESS (T) ± 0.005 (0.127)	A ± 0.005	B ± 0.005	C ± 0.005	E ± 0.005
Style A (3-sided wraparound)	0.250	0.126	0.025	0.025	0.025	0.040	0.046
Style B (top only)	0.240	0.126	0.025	0.025	0.025	0.040	-

**DERATING CURVE**



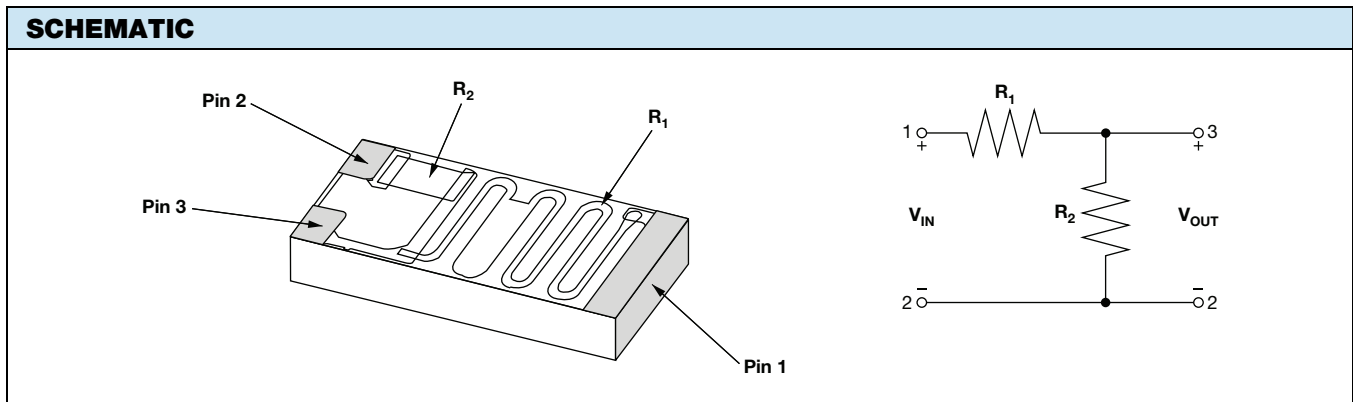
**Note**

- Reference only: not for all values specified. Consult factory for your specific value.

TYPE	TERMINATION MATERIAL	TERMINATION STYLE	TERMINATION STYLE / MATERIAL CODE	SOLDER TERMINATION CODE
Solderable	Nickel barrier	3-sided (wraparound)	AF	E or T (standard); F or S (optional) <sup>(1)</sup>
		Top only (flip chip)	BF	
Solderable	Non-magnetic	3-sided (wraparound)	AG	E or T (standard); F or S (optional) <sup>(1)</sup>
		Top only (flip chip)	BG	
Epoxy bondable / solderable	Platinum palladium gold	Top only (flip chip)	BE	N (standard); F or S (optional) <sup>(2)</sup>
Wire bondable / epoxy bondable	Gold	Top only (flip chip)	BC	N
Epoxy bondable	Palladium silver <sup>(3)</sup>	Top only (flip chip)	BA	N
	Platinum gold		BB	
	Platinum silver		BD	

**Notes**

- (1) Standard solder plating for the nickel barrier and non-magnetic parts is solder terminations E or T. Hot solder dipped terminations F or S are also available.
- (2) Use solder termination N for applications requiring epoxy bondable mounting, and solder terminations F or S for applications requiring solderable mounting.
- (3) While not recommended, palladium silver terminations could be used for solderable applications when using a solder alloy containing silver. If the solder paste being used to solder the palladium silver terminated parts to the boards does not have a silver-based composition, then the silver in the terminations could begin to leach when it is exposed to liquidus non-silver-based solders, causing the potential for solderability and/or solder joint issues.





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